



SBR2U30SA

2.0A SBR[®] SURFACE MOUNT SUPER BARRIER RECTIFIER

Features

- Ultra Low Forward Voltage Drop
- Patented Super Barrier Rectifier Technology
- Soft, Fast Switching Capability
- 150°C Operating Junction Temperature
- Lead Free Finish, RoHS Compliant (Note 1)
- Green Molding Compound (No Halogen and Antimony) (Note 5)

Mechanical Data

- Case: SMA
- Case Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Lead Free Plating (Matte Tin Finish.) Solderable per MIL-STD-202, Method 208 ⁽³⁾
- Polarity Indicator: Cathode Band
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.064 grams (approximate)







Bottom View

Maximum Ratings $@T_A = 25^{\circ}C$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{RM}	30	V
RMS Reverse Voltage	V _{R(RMS)}	21	V
Average Rectified Output Current (See Figure 1)	lo	2.0	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	30	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance Thermal Resistance Junction to Soldering (Note 2) Thermal Resistance Junction to Ambient (Note 3)	R _θ JS R _{θJA}	5 128	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	٥C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 4)	V _{(BR)R}	30	-	V	I _R = 400 μA
Forward Voltage Drop		0.21	0.26		I _F = 0.1A, T _J = 25°C
		0.11	0.15		I _F = 0.1A, T _J = 125°C
		0.31	0.35		I _F = 1.0A, T _J = 25°C
	VF	0.23	0.30		I _F = 1.0A, T _J = 125°C
		0.36	0.40		I _F = 2.0A, T _J = 25°C
		0.30	0.33		I _F = 2.0A, T _J = 125°C
Leakage Current (Note 4)		210	500	μΑ	V _R = 30V, T _J = 25 °C
	I _R	23	100	mA	V _R = 30V, T _J = 125 °C

Notes: 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied. Please visit our website at http://www.diodes.com/quality/lead_free.html.

2. Theoretical Reus calculated from the top center of the die straight down to the PCB cathode tab solder junction.

3. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf. T_A = 25°C

4. Short duration pulse test used to minimize self-heating effect.

5. Product manufactured with Data Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.

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SBR2U30SA

150

0.2

1

10

15

V_R, DC REVERSE VOLTAGE (V)

Fig. 6 Operating Temperature Derating

20

25

V_R, DC REVERSE VOLTAGE (V)

Fig. 4 Total Capacitance vs. Reverse Voltage

= 85°C

25°C

0.4

V_F, INSTANTANEOUS FORWARD VOLTAGE (V) Fig. 2 Typical Forward Characteristics

0.6

10

0.8

100

 $= -55^{\circ}$

 $T_A = 125^{\circ}C$

10

1

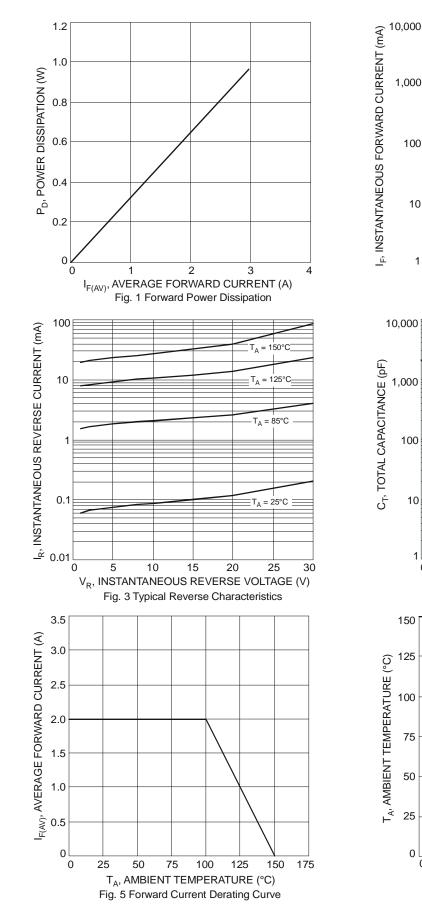
1 0.1

0

0

5

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NEW PRODUCT

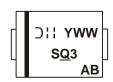


Ordering Information (Note 6)

Part Number	Case	Packaging
SBR2U30SA –13	SMA	5000/Tape & Reel

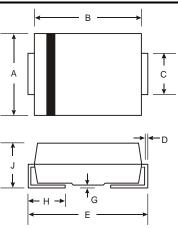
Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



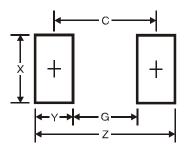
 $\begin{array}{l} \underline{SQ3} = Product Type Marking Code\\ \hline Dill = Manufacturers' code marking\\ \hline YWW = Date Code Marking\\ \hline Y = Last digit of year (ex: 7 for 2007)\\ \hline WW = Week code 01 to 52\\ \hline AB = Foundry and Assembly Code \end{array}$

Package Outline Dimensions



SMA				
Dim	Min	Max		
Α	2.29	2.92		
В	4.00	4.60		
C	1.27	1.63		
D	0.15	0.31		
ш	4.80	5.59		
G	0.05	0.20		
H	0.76	1.52		
J	2.01	2.30		
All Dimensions in mm				

Suggested Pad Layout



Dimensions	Value (in mm)
Z	6.5
G	1.5
Х	1.7
Y	2.5
C	4.0

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